

(19) KOREAN INTELLECTUAL PROPERTY OFFICE(KR)
(12) Registered Patent Gazette(B1)

(45) Pub. Date October 16, 2014
(11) Patent No. 10-1451266
(24) Reg. Date October 8, 2014

(51) Int. Cl: H01L 33/62 (2010.01)
H01L33/64(2010.01)
H01L 33/48 (2010.01)

(21) Application number:	10-2012-7019289
(22) Application date(Int'l):	2011.02.07
Exam. Request Date	2012.7.20
(85) Filing Date of Trans.	2012.7.20
(65) Publication No.	10-2012-0094526
(43) Publication Date	2012.8.24
(86) Int'l Filing No.	PCT/US2011/023924
(87) Int'l Publication No.	WO 2011/097576
Int'l Publication Date	2011.08.11
(30) Priority	
13/019,900	2011.02.02 (US)

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(56) Prior Arts
JP2006310817A*
JP2009071269A*
KR1020050031705A*
* cited by Examiner

Number of claims:
Total 4 claims

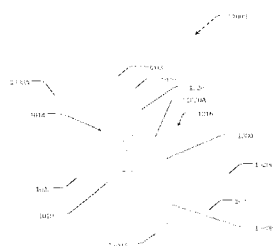
Examiner: KU, YOUNG HOE

TITLE OF INVENTION : LED LIGHT MODULE

[illegible]

A light emitting module is disclosed. The light emitting module includes a lead frame body, lead frame, a heat spreader, an intermediate heat sink, and at least one light emitting element (LED). The lead frame body defines a cavity which accurately registers the heat spreader and includes optical or reflective walls surrounding the light emitting elements soldered on metallized traces of the heat spreader. The lead frame body encases and supports portions of the lead frame. The lead frame extends from outside the body into the cavity to accurately align with solder pads of the heat spreader. All the pre-aligned mechanical, thermal and electrical contacts are then soldered by solder reflow process under tight environmental control to prevent damage to the light emitting element. A robust, healthy 3-dimensional optical-electro-mechanical assembly having a very low thermal resistance in a thermal path from its light emitting element to its intermediate heatsink is created.

- fig. 1



(30) Priority
61/302,474

2010.2.8(US)

